SCLS149C - DECEMBER 1982 - REVISED DECEMBER 2002

- Wide Operating Voltage Range of 2 V to 6 V
- High-Current 3-State Outputs Can Drive Up To 15 LSTTL Loads
- Low Power Consumption, 80-μA Max I<sub>CC</sub>
- Typical t<sub>pd</sub> = 8 ns
- ±6-mA Output Drive at 5 V
- Low Input Current of 1 μA Max
- Lock Bus-Latch Capability
- True Logic

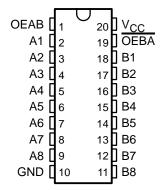
#### description/ordering information

These octal bus transceivers are designed for asynchronous two-way communication between data buses. The control-function implementation allows for maximum flexibility in timing.

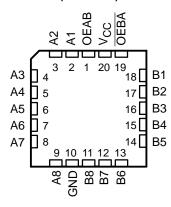
The 'HC623 devices allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending upon the logic levels at the output-enable (OEAB and OEBA) inputs.

OEAB and OEBA disable the device so that the buses are effectively isolated. The dual-enable configuration gives the transceivers the capability to store data by simultaneously enabling OEAB and OEBA. Each output reinforces its input in this transceiver configuration. When both OEAB and OEBA are enabled and all other data sources to the two sets of bus lines are in the high-impedance state, both sets of bus lines (16 total) remain at their last states. The 8-bit codes appearing on the two sets of buses are identical.

#### SN54HC623 . . . J OR W PACKAGE SN74HC623 . . . DW, N, OR NS PACKAGE (TOP VIEW)



# SN54HC623 . . . FK PACKAGE (TOP VIEW)



#### ORDERING INFORMATION

TA	PACK	AGE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube	SN74HC623N	SN74HC623N
-40°C to 85°C	COIC DW	Tube	SN74HC623DW	LICCOS
-40°C to 85°C	SOIC - DW	Tape and reel	SN74HC623DWR	HC623
	SOP - NS	Tape and reel	SN74HC623NSR	HC623
	CDIP – J Tube		SNJ54HC623J	SNJ54HC623J
−55°C to 125°C	CFP – W	Tube	SNJ54HC623W	SNJ54HC623W
	LCCC - FK	Tube	SNJ54HC623FK	SNJ54HC623FK

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



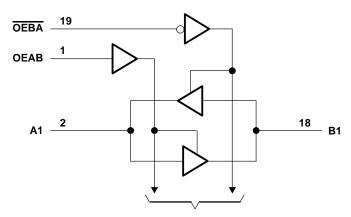
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#### **FUNCTION TABLE**

INP	UTS	ODEDATION
OEBA	OEAB	OPERATION
L	L	B data to A bus
Н	Н	A data to B bus
Н	L	Isolation
L	Н	B data to A bus, A data to B bus

#### logic diagram (positive logic)



**To Seven Other Transceivers** 

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>		0.5 V to 7	7 V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) (see	ee Note 1)	±20 r	nΑ
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CO</sub>	C) (see Note 1)	) ±20 r	nΑ
Continuous output current, $I_O(V_O = 0 \text{ to } V_{CC})$		±35 r	nΑ
Continuous current through V <sub>CC</sub> or GND		±70 r	nΑ
Package thermal impedance, θ <sub>JA</sub> (see Note 2)	: DW package	9	/W
	N package	69°C	/W
	NS package	60°C	/W
Storage temperature range, T <sub>stq</sub>		–65°C to 150	°С

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
  - 2. The package thermal impedance is calculated in accordance with JESD 51-7.



### recommended operating conditions (see Note 3)

			SN	154HC62	23	SN	174HC62	23	LINUT
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage		2	5	6	2	5	6	V
		V <sub>CC</sub> = 2 V	1.5			1.5			
VIH	High-level input voltage	V <sub>CC</sub> = 4.5 V	3.15			3.15			V
		V <sub>CC</sub> = 6 V	4.2		ih	4.2			
		V <sub>CC</sub> = 2 V		Ą	0.5			0.5	
VIL	Low-level input voltage	V <sub>CC</sub> = 4.5 V		96	1.35			1.35	V
		VCC = 6 V		6	1.8			1.8	
VI	Input voltage		0 2	5	VCC	0		VCC	V
٧o	Output voltage		0		VCC	0		VCC	V
		V <sub>CC</sub> = 2 V	Q.		1000			1000	
Δt/Δν	Input transition rise/fall time	V <sub>CC</sub> = 4.5 V			500			500	ns
		VCC = 6 V			400			400	
TA	Operating free-air temperature		-55		125	-40		85	°C

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		<b>TEST 66</b>	NO TIONS	.,	Т	A = 25°C	;	SN54H	IC623	SN74H	IC623	
PAR	AMETER	TEST CO	NDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
				2 V	1.9	1.998		1.9		1.9		
			$I_{OH} = -20  \mu A$	4.5 V	4.4	4.499		4.4		4.4		
VOH		VI = VIH or VIL		6 V	5.9	5.999		5.9		5.9		V
			$I_{OH} = -6 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84		
			$I_{OH} = -7.8 \text{ mA}$	6 V	5.48	5.8		5.2	!h	5.34		
				2 V		0.002	0.1		0.1		0.1	
			I <sub>OL</sub> = 20 μA	4.5 V		0.001	0.1	4	0.1		0.1	
VOL		$V_I = V_{IH}$ or $V_{IL}$		6 V		0.001	0.1	C)	0.1		0.1	V
			I <sub>OL</sub> = 6 mA	4.5 V		0.17	0.26	20	0.4		0.33	
	=		$I_{OL} = 7.8 \text{ mA}$	6 V		0.15	0.26	O <sub>V</sub>	0.4		0.33	
IJ	OEAB or OEBA	V <sub>I</sub> = V <sub>CC</sub> or 0		6 V		±0.1	±100	7	±1000		±1000	nA
loz	A or B	VO = VCC or 0		6 V		±0.01	±0.5		±10		±5	μΑ
Icc	_	$V_I = V_{CC}$ or 0,	I <sub>O</sub> = 0	6 V			8		160		80	μΑ
Ci	OEAB or OEBA			2 V to 6 V		3	10		10		10	pF

# switching characteristics over recommended operating free-air temperature range, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

	FROM	то		Τ <sub>Δ</sub>	\ = 25°C	;	SN54H	IC623	SN74H	C623	
PARAMETER	(INPUT)	(OUTPUT)	vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V		29	105		160		130	
t <sub>pd</sub>	A or B	B or A	4.5 V		10	21		32		26 ns	
·			6 V		8	18		27		22	
			2 V		112	210		315		265	
t <sub>en</sub>	OEBA	Α	4.5 V		27	42		63		53	ns
			6 V		20	36		54		45	
			2 V		40	150		225		190	
<sup>t</sup> dis	OEBA	Α	4.5 V		18	30		45		38 ns	ns
			6 V		16	26	.<	38		32	ļ
			2 V		112	210	Ź	315		265	
t <sub>en</sub>	OEAB	В	4.5 V		27	42	20	63		53	ns
			6 V		20	36	Q.	54		45	
			2 V		40	150		225		190	
<sup>t</sup> dis	OEAB	В	4.5 V		18	30		45		38	ns
			6 V		16	26		38		32	
			2 V		20	60		90		75	
t <sub>t</sub>		A or B	4.5 V		8	12		18		15	ns
			6 V		6	10		15		13	

# switching characteristics over recommended operating free-air temperature range, $C_L$ = 150 pF (unless otherwise noted) (see Figure 1)

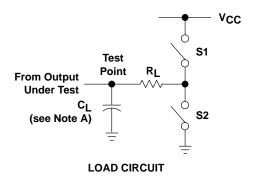
	FROM	то		T,	\ = 25°C	;	SN54H	C623	SN74H	IC623											
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT										
			2 V		44	135		200		170											
<sup>t</sup> pd	A or B	B or A	4.5 V		14	27		40		34	ns										
•			6 V		11	23		34		29											
			2 V		130	270		405		335											
	OEBA	Α	4.5 V		31	54		81		67	ns										
			6 V		23	46	Q	69													
t <sub>en</sub>		В	2 V		130	270	0,	405		335											
	OEAB		В	В	В	В	В	В	В	В	В	В	В	4.5 V		31	54	<sup>l</sup> q <sub>C</sub>	81		67
			6 V		23	46	V <sub>Q</sub>	69		56											
			2 V		45	210		315		265											
t <sub>t</sub>	A or B	A or B	A or B	A or B	A or B	A or B	A or B	A or B	A or B	4.5 V		17	42		63		53	ns			
•			6 V		13	36		53		45											

# operating characteristics, $T_A = 25^{\circ}C$

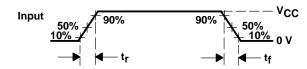
PARAMETER	TEST CONDITIONS	TYP	UNIT
C <sub>pd</sub> Power dissipation capacitance per transceiver	No load	40	pF



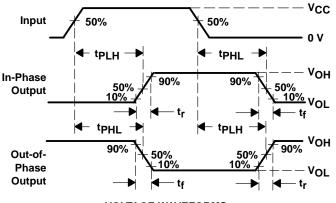
#### PARAMETER MEASUREMENT INFORMATION

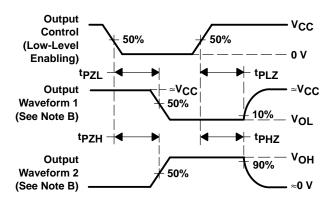


PARAI	METER	RL	CL	S1	S2
	tPZH	1 <b>k</b> Ω	50 pF or	Open	Closed
<sup>t</sup> en	tPZL	1 K22	150 pF	Closed	Open
	tPHZ	<b>1 k</b> Ω	50 pF	Open	Closed
<sup>t</sup> dis	tPLZ	1 K22	50 pr	Closed	Open
t <sub>pd</sub> or	t <sub>pd</sub> or t <sub>t</sub>		50 pF or 150 pF	Open	Open



# VOLTAGE WAVEFORM INPUT RISE AND FALL TIMES





VOLTAGE WAVEFORMS
PROPAGATION DELAY AND OUTPUT TRANSITION TIMES

VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES FOR 3-STATE OUTPUTS

NOTES: A. C<sub>L</sub> includes probe and test-fixture capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_{O} = 50 \Omega$ ,  $t_{f} = 6 \text{ ns}$ .
- D. The outputs are measured one at a time with one input transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tplH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms







www.ti.com 28-Aug-2010

#### **PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/ Ball Finish	MSL Peak Temp <sup>(3)</sup>	Samples (Requires Login)
SN74HC623DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
SN74HC623DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
SN74HC623N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	Contact TI Distributor or Sales Office
SN74HC623NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	Contact TI Distributor or Sales Office
SN74HC623NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
SN74HC623NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
SN74HC623NSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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## **PACKAGE OPTION ADDENDUM**

28-Aug-2010

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PACKAGE MATERIALS INFORMATION

www.ti.com 23-Jul-2010

### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC623NSR	SO	NS	20	2000	330.0	24.4	8.2	13.0	2.5	12.0	24.0	Q1

**PACKAGE MATERIALS INFORMATION** 

www.ti.com 23-Jul-2010



#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC623NSR	SO	NS	20	2000	346.0	346.0	41.0

# N (R-PDIP-T\*\*)

## PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



# DW (R-PDSO-G20)

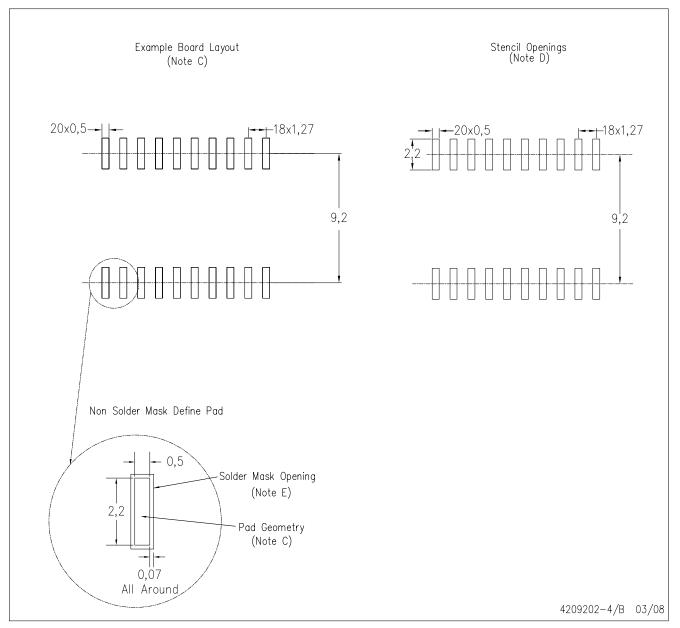
# PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AC.



# DW (R-PDSO-G20)



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC—7525
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



### **MECHANICAL DATA**

## NS (R-PDSO-G\*\*)

# 14-PINS SHOWN

#### PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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Clocks and Timers	www.ti.com/clocks	Consumer Electronics	www.ti.com/consumer-apps
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RF/IF and ZigBee® Solutions	www.ti.com/lprf	Video and Imaging	www.ti.com/video
		Wireless	www.ti.com/wireless-apps